General Description

PSoC® 4 is a scalable and reconfigurable platform architecture for a family of mixed-signal programmable embedded system controllers with an ARM® Cortex™-M0 CPU. It combines programmable and re-configurable analog and digital blocks with flexible automatic routing. The PSoC 4200 product family, based on this platform, is a combination of a microcontroller with digital programmable logic, high-performance analog-to-digital conversion, opamps with Comparator mode, and standard communication and timing peripherals. The PSoC 4200 products will be fully upward compatible with members of the PSoC 4 platform for new applications and design needs. The programmable analog and digital sub-systems allow flexibility and in-field tuning of the design.

Features

32-bit MCU Sub-system

- 48 MHz ARM Cortex-M0 CPU with single cycle multiply
- Up to 32 kB of flash with Read Accelerator
- Up to 4 kB of SRAM

Programmable Analog

- Two opamps with reconfigurable high-drive external and high-bandwidth internal drive and Comparator modes and ADC input buffering capability
- 12-bit 1 Msps SAR ADC with differential and single-ended modes and Channel Sequencer with signal averaging
- Two current DACs (IDACs) for general-purpose or capacitive sensing applications on any pin
- Two low-power comparators that operate in Deep Sleep

Programmable Digital

- Four programmable logic blocks, each with 8 Macrocells and data path (called universal digital blocks, UDBs)
- Cypress provided peripheral component library, user-defined state machines, and Verilog input

Low Power 1.71 to 5.5 V operation

- 20 nA Stop Mode with GPIO pin wakeup
- Hibernate and Deep Sleep modes allow wakeup-time versus power trade-offs

Capacitive Sensing

- Cypress Capacitive Sigma-Delta (CSD) provides best-in-class SNR (>5:1) and water tolerance
- Cypress supplied software component makes capacitive sensing design easy
- Automatic hardware tuning (SmartSense™)

Segment LCD Drive

- LCD drive supported on all pins (common or segment)
- Operates in Deep Sleep mode with 4 bits per pin memory

Serial Communication

- Two independent run-time reconfigurable Serial Communication Blocks (SCBs) with re-configurable I2C, SPI, or UART functionality

Timing and Pulse-Width Modulation

- Four 16-bit Timer/Counter Pulse-Width Modulator (TCPWM) blocks
- Center-aligned, Edge, and Pseudo-random modes
- Comparator-based triggering of Kill signals for motor drive and other high reliability digital logic applications

Up to 36 Programmable GPIO

- 44-pin TQFP, 40-pin QFN, and 28-pin SSOP packages.
- Any GPIO Pin can be Capsense, LCD, Analog, or Digital
- Drive modes, strengths, and slew rates are programmable

PSoC Creator Design Environment

- Integrated Development Environment provides schematic design entry and build (with analog and digital automatic routing)
- Applications Programming Interface (API Component) for all fixed-function and programmable peripherals
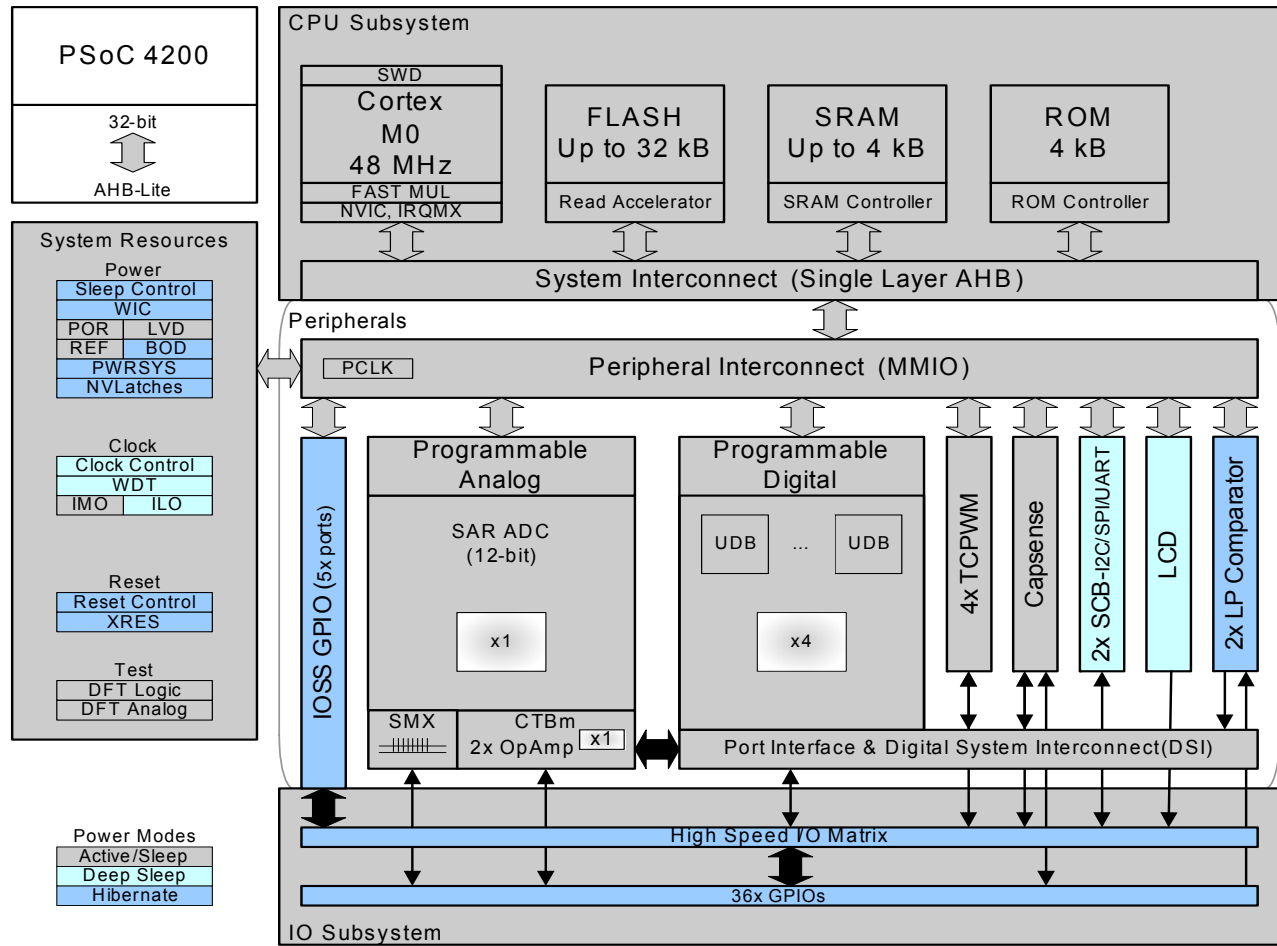
Industry Standard Tool Compatibility

- After schematic entry, development can be done with ARM-based industry-standard development tools

Contents

Block Diagram

PSoC 4200 devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial_Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator Integrated Development Environment (IDE) provides fully integrated programming and debug support for PSoC 4200 devices. The SWD interface is fully compatible with industry standard third party tools. With the ability to disable debug features, with very robust flash protection, and by allowing customer-proprietary functionality to be implemented in on-chip programmable blocks, the PSoC 4200 family provides a level of security not possible with multi-chip application solutions or with microcontrollers.

The debug circuits are enabled by default and can only be disabled in firmware. If not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. Because all programming, debug, and test interfaces are disabled when maximum device security is enabled, PSoC 4200 with device security enabled may not be returned for failure analysis. This is a trade-off the PSoC 4200 allows the customer to make.

Functional Definition

CPU and Memory Subsystem

CPU

The Cortex-M0 CPU in the PSoC 4200 is part of the 32-bit MCU subsystem, which is optimized for low power operation with extensive clock gating. It mostly uses 16-bit instructions and executes a subset of the Thumb-2 instruction set. This enables fully compatible binary upward migration of the code to higher performance processors such as the Cortex-M3 and M4, thus enabling upward compatibility. The Cypress implementation includes a hardware multiplier that provides a 32-bit result in one cycle. It includes a nested vectored interrupt controller (NVIC) block with 32 interrupt inputs and also includes a Wakeup Interrupt Controller (WIC), which can wake the processor up from Deep Sleep mode allowing power to be switched off to the main processor when the chip is in Deep Sleep mode. The Cortex-M0 CPU provides a Non-Maskable Interrupt input (NMI), which is made available to the user when it is not in use for system functions requested by the user.

The CPU also includes a debug interface, the Serial Wire Debug (SWD) interface, which is a 2-wire form of JTAG; the debug configuration used for PSoC 4200 has four break-point (address) comparators and two watchpoint (data) comparators.

Flash

The PSoC 4200 has a flash module with a flash accelerator tightly coupled to the CPU to improve average access times from the flash block. The flash block is designed to deliver 1 wait-state (WS) access time at 48 MHz and with 0 WS access time at 24 MHz. The flash accelerator delivers 85% of single-cycle SRAM access performance on average. Part of the flash module can be used to emulate EEPROM operation if required.

SRAM

SRAM memory is retained during Hibernate.

SROM

A supervisory ROM that contains boot and configuration routines is provided.

System Resources

Power System

The power system is described in detail in the section Power on page 12. It provides assurance that voltage levels are as required for each respective mode and either delay mode entry (on power-on reset (POR), for example) until voltage levels are as required for proper function or generate resets (Brown-Out Detect (BOD)) or interrupts (Low Voltage Detect (LVD)). The PSoC 4200 operates with a single external supply over the range of 1.71 to 5.5 V and has five different power modes, transitions between which are managed by the power system. The PSoC 4200 provides Sleep, Deep Sleep, Hibernate, and Stop low-power modes.

Clock System

The PSoC 4200 clock system is responsible for providing clocks to all subsystems that require clocks and for switching between different clock sources without glitching. In addition, the clock system ensures that no metastable conditions occur.

The clock system for the PSoC 4200 consists of the IMO and the ILO internal oscillators and provision for an external clock.

Figure 1. PSoC 4200 MCU Clocking Architecture
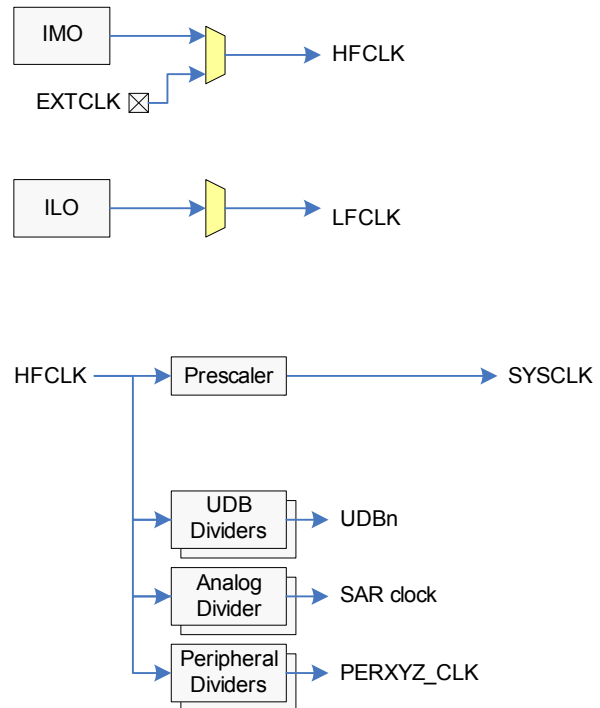
The HFCLK signal can be divided down (see PSoC 4200 MCU Clocking Architecture) to generate synchronous clocks for the UDBs, and the analog and digital peripherals. There are a total of 12 clock dividers for the PSoC 4200, each with 16-bit divide capability; this allows eight to be used for the fixed-function blocks and four for the UDBs. The analog clock leads the digital clocks to allow analog events to occur before digital clock-related noise is generated. The 16-bit capability allows a lot of flexibility in generating fine-grained frequency values and is fully supported in PSoC Creator. When UDB-generated Pulse Interrupts are used, SYSCLK must equal HFCLK.

IMO Clock Source

The IMO is the primary source of internal clocking in the PSoC 4200. It is trimmed during testing to achieve the specified accuracy. Trim values are stored in nonvolatile latches (NVL). Additional trim settings from flash can be used to compensate for changes. The IMO default frequency is 24 MHz and it can be adjusted between 3 to 48 MHz in steps of 1 MHz. IMO Tolerance with Cypress-provided calibration settings is ±2%.

ILO Clock Source

The ILO is a very low power oscillator, which is primarily used to generate clocks for peripheral operation in Deep Sleep mode. ILO-driven counters can be calibrated to the IMO to improve accuracy. Cypress provides a software component, which does the calibration.

Watchdog Timer

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the timeout occurs. The watchdog reset is recorded in the Reset Cause register.

Reset

The PSoC 4200 can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the Reset. An XRES pin is reserved for external reset to avoid complications with configuration and multiple pin functions during power-on or reconfiguration.

Voltage Reference

The PSoC 4200 reference system generates all internally required references. A 1% voltage reference spec is provided for the 12-bit ADC. To allow better signal to noise ratios (SNR) and better absolute accuracy, it is possible to bypass the internal reference using a GPIO pin or to use an external reference for the SAR.

Analog Blocks

12-bit SAR ADC

The 12-bit 1 MSample/second SAR ADC can operate at a maximum clock rate of 18 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion.

The block functionality is augmented for the user by adding a reference buffer to it (trimmable to ±1%) and by providing the choice (for the PSoC 4200 case) of three internal voltage references: V_{DD}, $V_{DD}/2$, and V_{REF} (nominally 1.024 V) as well as an external reference through a GPIO pin. The Sample-and-Hold (S/H) aperture is programmable allowing the gain bandwidth requirements of the amplifier driving the SAR inputs, which determine its settling time, to be relaxed if required. System performance will be 65 dB for true 12-bit precision providing appropriate references are used and system noise levels permit. To improve performance in noisy conditions, it is possible to provide an external bypass (through a fixed pin location) for the internal reference amplifier.

The SAR is connected to a fixed set of pins through an 8-input sequencer. The sequencer cycles through selected channels autonomously (sequencer scan) and does so with zero switching overhead (that is, aggregate sampling bandwidth is equal to 1 Msps whether it is for a single channel or distributed over several channels). The sequencer switching is effected through a state machine or through firmware driven switching. A feature provided by the sequencer is buffering of each channel to reduce CPU interrupt service requirements. To accommodate signals with varying source impedance and frequency, it is possible to have different sample times programmable for each channel. Also, signal range specification through a pair of range registers (low and high range values) is implemented with a corresponding out-of-range interrupt if the digitized value exceeds the programmed range; this allows fast detection of out-of-range values without the necessity of having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software.

The SAR is able to digitize the output of the on-board temperature sensor for calibration and other temperature-dependent functions. The SAR is not available in Deep Sleep and Hibernate modes as it requires a high-speed clock (up to 18 MHz). The SAR operating range is 1.71 to 5.5 V.

Figure 2. SAR ADC System Diagram
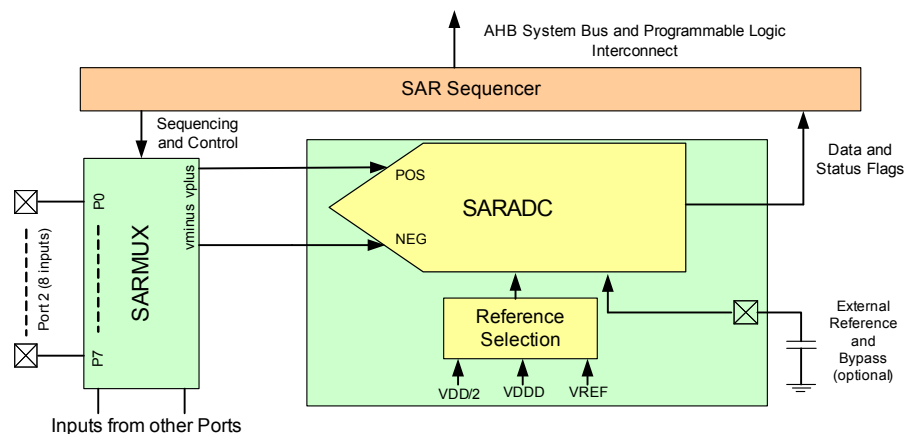
Two Opamps (CTBm Block)

The PSoC 4200 has two opamps with Comparator modes which allow most common analog functions to be performed on-chip eliminating external components; PGAs, Voltage Buffers, Filters, Trans-Impedance Amplifiers, and other functions can be realized with external passives saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the Sample-and-Hold circuit of the ADC without requiring external buffering.

Temperature Sensor

The PSoC 4200 has one on-chip temperature sensor This consists of a diode, which is biased by a current source that can be disabled to save power. The temperature sensor is connected to the ADC, which digitizes the reading and produces a temperature value using Cypress supplied software that includes calibration and linearization.

Low-power Comparators

The PSoC 4200 has a pair of low-power comparators, which can also operate in the Deep Sleep and Hibernate modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode (Hibernate) where the system wake-up circuit is activated by a comparator switch event.

Programmable Digital

Universal Digital Blocks (UDBs) and Port Interfaces

The PSoC 4200 has four UDBs; the UDB array also provides a switched Digital System Interconnect (DSI) fabric that allows signals from peripherals and ports to be routed to and through the UDBs for communication and control. The UDB array is shown in the following figure.

Figure 3. UDB Array
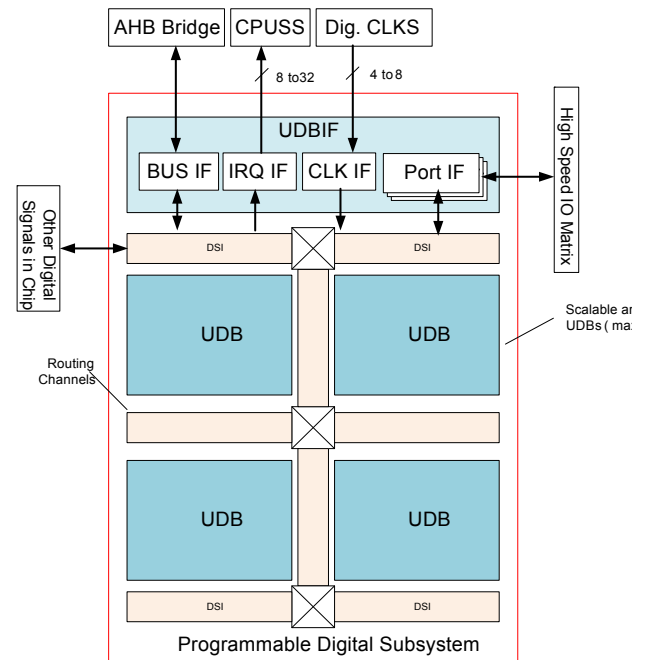
UDBs can be clocked from a clock divider block, from a port interface (required for peripherals such as SPI), and from the DSI network directly or after synchronization.

A port interface is defined, which acts as a register that can be clocked with the same source as the PLDs inside the UDB array. This allows faster operation because the inputs and outputs can be registered at the port interface close to the I/O pins and at the edge of the array. The port interface registers can be clocked by one of the I/Os from the same port. This allows interfaces such as SPI to operate at higher clock speeds by eliminating the delay for the port input to be routed over DSI and used to register other inputs (see Figure 4).

Figure 4. Port Interface
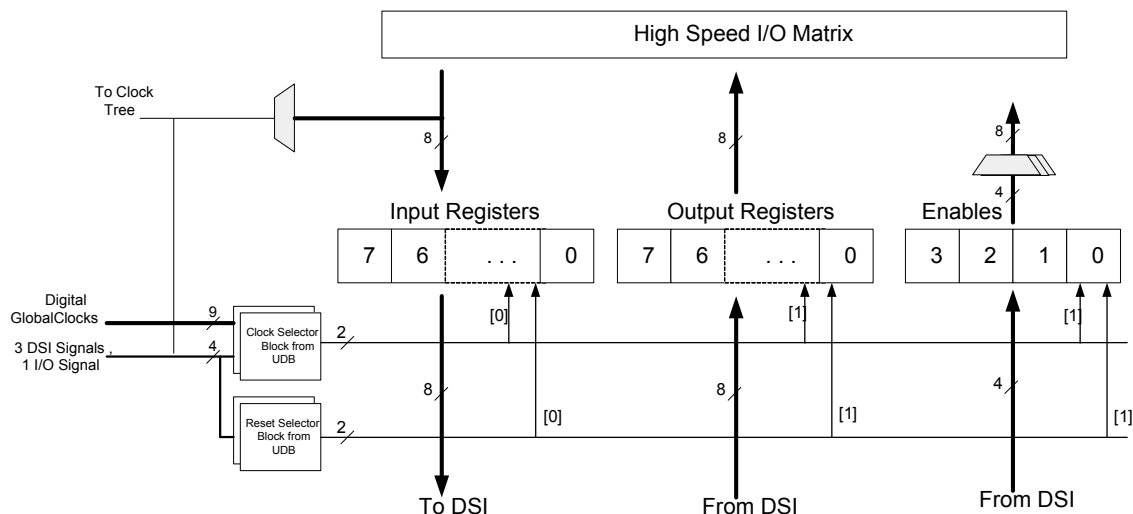
The UDBs can generate interrupts (one UDB at a time) to the interrupt controller. The UDBs retain the ability to connect to any pin on the chip through the DSI.

Fixed Function Digital

Timer/Counter/PWM Block

The Timer/Counter/PWM block consists of four 16-bit counters with user-programmable period length. There is a Capture register to record the count value at the time of an event (which may be an I/O event), a period register which is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals which are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as deadband programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an overcurrent state is indicated and the PWMs driving the FETs need to be shut off immediately with no time for software intervention.

Serial Communication Blocks (SCB)

The PSoC 4200 has two SCBs, which can each implement an I^{2}C, UART, or SPI interface.

I^{2}C Mode: The hardware I^{2}C block implements a full multi-master and slave interface (it is capable of multimaster arbitration). This block is capable of operating at speeds of up to 1 Mbps (Fast Mode Plus) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EzI^{2}C that creates a mailbox address range in the memory of the PSoC 4200 and effectively reduces I^{2}C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time. The FIFO mode is available in all channels and is very useful in the absence of DMA.

The I^{2}C peripheral is compatible with the I^{2}C Standard-mode, Fast-mode, and Fast-mode Plus devices as defined in the NXP I^{2}C-bus specification and user manual (UM10204). The I^{2}C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4200 is not completely compliant with the I^{2}C spec in the following respects:

- GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I^{2}C system.

- Fast-mode Plus has an I_{OL} specification of 20 mA at a V_{OL} of 0.4 V. The GPIO cells can sink a maximum of 8 mA I_{OL} with a V_{OL} maximum of 0.6 V.

- Fast-mode and Fast-mode Plus specify minimum Fall times, which are not met with the GPIO cell; Slow strong mode can help meet this spec depending on the Bus Load.

- When the SCB is an I^{2}C Master, it interposes an IDLE state between NACK and Repeated Start; the I^{2}C spec defines Bus free as following a Stop condition so other Active Masters do not intervene but a Master that has just become activated may start an Arbitration cycle.

- When the SCB is in I^{2}C Slave mode, and Address Match on External Clock is enabled (EC_AM = 1) along with operation in the internally clocked mode (EC_OP = 0), then its I^{2}C address must be even.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated. Note that hardware handshaking is not supported. This is not commonly used and can be implemented with a UDB-based UART in the system, if required.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (essentially adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO and also supports an EzSPI mode in which data interchange is reduced to reading and writing an array in memory.

GPIO

The PSoC 4200 has 36 GPIOs. The GPIO block implements the following:

- Eight drive strength modes:
  - Analog input mode (input and output buffers disabled)
  - Input only
  - Weak pull-up with strong pull-down
  - Strong pull-up with weak pull-down
  - Open drain with strong pull-down
  - Open drain with strong pull-up
  - Strong pull-up with strong pull-down
  - Weak pull-up with weak pull-down

- Input threshold select (CMOS or LVTTL).

- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes.

- Hold mode for latching previous state (used for retaining I/O state in Deep Sleep mode and Hibernate modes).

- Selectable slew rates for dV/dt related noise control to improve EMI.

The pins are organized in logical entities called ports, which are 8-bit in width. During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin. Pin locations for fixed-function peripherals are also fixed to reduce internal multiplexing complexity (these signals do not go through the DSI network). DSI signals are not affected by this and any pin may be routed to any UDB through the DSI network.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4200 since it has 4.5 ports).

Special Function Peripherals

LCD Segment Drive

The PSoC 4200 has an LCD controller which can drive up to four commons and up to 32 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as digital correlation and PWM.

Digital correlation pertains to modulating the frequency and levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays.

PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).

CapSense

CapSense is supported on all pins in the PSoC 4200 through a CapSense Sigma-Delta (CSD) block that can be connected to any pin through an analog mux bus that any GPIO pin can be connected to via an Analog switch. CapSense function can thus be provided on any pin or group of pins in a system under software control. A component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another Mux Bus to provide water tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input.

The CapSense block has two IDACs which can be used for general purposes if CapSense is not being used.(both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

Pinouts

The following is the pin-list for the PSoC 4200. Port 2 comprises of the high-speed Analog inputs for the SAR Mux. P1.7 is the optional external input and bypass for the SAR reference. Ports 3 and 4 contain the Digital Communication channels. All pins support CSD Capsense and Analog Mux Bus connections.

Pins		44-TQFP		40-QFN		28-SSOP		Alternate Functions for Pins					Pin Description
Name	Type	Pin	Name	Pin	Name	Pin	Name	Analog	Alt 1	Alt 2	Alt 3	Alt 4	
VSSD	Power	1(DN)	VSS	DN	–	DN	–	–	–	–	–	–	Digital Ground
P2.0	GPIO	2	P2.0	1	P2.0	–	–	sarmux.0	–	–	–	–	Port 2 Pin 0: gpio, lcd, csd, sarmux
P2.1	GPIO	3	P2.1	2	P2.1	–	–	sarmux.1	–	–	–	–	Port 2 Pin 1: gpio, lcd, csd, sarmux
P2.2	GPIO	4	P2.2	3	P2.2	5	P2.2	sarmux.2	–	–	–	–	Port 2 Pin 2: gpio, lcd, csd, sarmux
P2.3	GPIO	5	P2.3	4	P2.3	6	P2.3	sarmux.3	–	–	–	–	Port 2 Pin 3: gpio, lcd, csd, sarmux
P2.4	GPIO	6	P2.4	5	P2.4	7	P2.4	sarmux.4	tcpwm0_p[1]	–	–	–	Port 2 Pin 4: gpio, lcd, csd, sarmux, pwm
P2.5	GPIO	7	P2.5	6	P2.5	8	P2.5	sarmux.5	tcpwm0_n[1]	–	–	–	Port 2 Pin 5: gpio, lcd, csd, sarmux, pwm
P2.6	GPIO	8	P2.6	7	P2.6	9	P2.6	sarmux.6	tcpwm1_p[1]	–	–	–	Port 2 Pin 6: gpio, lcd, csd, sarmux, pwm
P2.7	GPIO	9	P2.7	8	P2.7	10	P2.7	sarmux.7	tcpwm1_n[1]	–	–	–	Port 2 Pin 7: gpio, lcd, csd, sarmux, pwm
–	–	10(DN)	VSS	9(DN)	VSS	–	–	–	–	–	–	–	Package pin to lead frame paddle downbond
P3.0	GPIO	11	P3.0	10	P3.0	11	P3.0	–	tcpwm0_p[0]	scb1_uart_rx[0]	scb1_i2c_scl[0]	scb1_spi_mosi[0]	Port 3 Pin 0: gpio, lcd, csd, pwm, scb1
P3.1	GPIO	12	P3.1	11	P3.1	12	P3.1	–	tcpwm0_n[0]	scb1_uart_tx[0]	scb1_i2c_sda[0]	scb1_spi_miso[0]	Port 3 Pin 1: gpio, lcd, csd, pwm, scb1
P3.2	GPIO	13	P3.2	12	P3.2	13	P3.2	–	tcpwm1_p[0]	–	swd_io	scb1_spi_clk[0]	Port 3 Pin 2: gpio, lcd, csd, pwm, scb1, swd
P3.3	GPIO	14	P3.3	13	P3.3	14	P3.3	–	tcpwm1_n[0]	–	swd_clk	scb1_spi_ssel_0[0]	Port 3 Pin 3: gpio, lcd, csd, pwm, scb1, swd
P3.4	GPIO	15	P3.4	14	P3.4	–	–	–	tcpwm2_p[0]	–	–	scb1_spi_ssel_1	Port 3 Pin 4: gpio, lcd, csd, pwm, scb1
P3.5	GPIO	16	P3.5	15	P3.5	–	–	–	tcpwm2_n[0]	–	–	scb1_spi_ssel_2	Port 3 Pin 5: gpio, lcd, csd, pwm, scb1
P3.6	GPIO	17	P3.6	16	P3.6	–	–	–	tcpwm3_p[0]	–	–	scb1_spi_ssel_3	Port 3 Pin 6: gpio, lcd, csd, pwm, scb1
P3.7	GPIO	18	P3.7	17	P3.7	–	–	–	tcpwm3_n[0]	–		–	Port 3 Pin 7: gpio, lcd, csd, pwm
VDDD	Power	19	VDDD	–	–	–	–	–	–	–	–	–	Digital Supply, 1.8 - 5.5 V
P4.0	GPIO	20	P4.0	18	P4.0	15	P4.0	–	–	scb0_uart_rx	scb0_i2c_scl	scb0_spi_mosi	Port 4 Pin 0: gpio, lcd, csd, scb0
P4.1	GPIO	21	P4.1	19	P4.1	16	P4.1	–	–	scb0_uart_tx	scb0_i2c_sda	scb0_spi_miso	Port 4 Pin 1: gpio, lcd, csd, scb0
P4.2	GPIO	22	P4.2	20	P4.2	17	P4.2	csd_c_mod	–	–	–	scb0_spi_clk	Port 4 Pin 2: gpio, lcd, csd, scb0
P4.3	GPIO	23	P4.3	21	P4.3	18	P4.3	csd_c_sh_tank	–	–	–	scb0_spi_ssel_0	Port 4 Pin 3: gpio, lcd, csd, scb0
P0.0	GPIO	24	P0.0	22	P0.0	19	P0.0	comp1_inp	–	–	–	scb0_spi_ssel_1	Port 0 Pin 0: gpio, lcd, csd, scb0, comp
P0.1	GPIO	25	P0.1	23	P0.1	20	P0.1	comp1_inn	–	–	–	scb0_spi_ssel_2	Port 0 Pin 1: gpio, lcd, csd, scb0, comp
P0.2	GPIO	26	P0.2	24	P0.2	21	P0.2	comp2_inp	–	–	–	scb0_spi_ssel_3	Port 0 Pin 2: gpio, lcd, csd, scb0, comp
P0.3	GPIO	27	P0.3	25	P0.3	22	P0.3	comp2_inn	–	–	–	–	Port 0 Pin 3: gpio, lcd, csd, comp
P0.4	GPIO	28	P0.4	26	P0.4	–	–	–	–	scb1_uart_rx[1]	scb1_i2c_scl[1]	scb1_spi_mosi[1]	Port 0 Pin 4: gpio, lcd, csd, scb1
P0.5	GPIO	29	P0.5	27	P0.5	–	–	–	–	scb1_uart_tx[1]	scb1_i2c_sda[1]	scb1_spi_miso[1]	Port 0 Pin 5: gpio, lcd, csd, scb1
P0.6	GPIO	30	P0.6	28	P0.6	23	P0.6	–	ext_clk	–	–	scb1_spi_clk[1]	Port 0 Pin 6: gpio, lcd, csd, scb1, ext_clk
P0.7	GPIO	31	P0.7	29	P0.7	24	P0.7	–	–	–	wakeup	scb1_spi_ssel_0[1]	Port 0 Pin 7: gpio, lcd, csd, scb1, wakeup

Pins		44-TQFP		40-QFN		28-SSOP		Alternate Functions for Pins					Pin Description
Name	Type	Pin	Name	Pin	Name	Pin	Name	Analog	Alt 1	Alt 2	Alt 3	Alt 4	
XRES	XRES	32	XRES	30	XRES	25	XRES	–	–	–	–	–	Chip reset, active low
VCCD	Power	33	VCCD	31	VCCD	26	VCCD	–	–	–	–	–	Regulated supply, connect to 1 µF cap or 1.8 V
VDDD	Power	34	VDDD	32	VDDD	27	VDD	–	–	–	–	–	Digital Supply, 1.8 - 5.5 V
VDDA	Power	35	VDDA	33	VDDA	27	VDD	–	–	–	–	–	Analog Supply, 1.8 - 5.5 V, equal to VDDD
VSSA	Power	36	VSSA	34	VSSA	28(DN)	VSS	–	–	–	–	–	Analog Ground
P1.0	GPIO	37	P1.0	35	P1.0	1	P1.0	ctb.oa0.inp	tcpwm2_p[1]	–	–	–	Port 1 Pin 0: gpio, lcd, csd, ctb, pwm
P1.1	GPIO	38	P1.1	36	P1.1	2	P1.1	ctb.oa0.inm	tcpwm2_n[1]	–	–	–	Port 1 Pin 1: gpio, lcd, csd, ctb, pwm
P1.2	GPIO	39	P1.2	37	P1.2	3	P1.2	ctb.oa0.out	tcpwm3_p[1]	–	–	–	Port 1 Pin 2: gpio, lcd, csd, ctb, pwm
P1.3	GPIO	40	P1.3	38	P1.3	–	–	ctb.oa1.out	tcpwm3_n[1]	–	–	–	Port 1 Pin 3: gpio, lcd, csd, ctb, pwm
P1.4	GPIO	41	P1.4	39	P1.4	–	–	ctb.oa1.inm	–	–	–	–	Port 1 Pin 4: gpio, lcd, csd, ctb
P1.5	GPIO	42	P1.5	–	–	–	–	ctb.oa1.inp	–	–	–	–	Port 1 Pin 5: gpio, lcd, csd, ctb
P1.6	GPIO	43	P1.6	–	–	–	–	ctb.oa0.inp_alt	–	–	–	–	Port 1 Pin 6: gpio, lcd, csd
P1.7	GPIO	44	P1.7	40	P1.7	4	P1.7	ctb.oa1.inp_alt ext_vref	–	–	–	–	Port 1 Pin 7: gpio, lcd, csd, ext_ref

Descriptions of the Pin functions are as follows:

VDDD: Power supply for both analog and digital sections (where there is no V_{DDA} pin).

VDDA: Analog V_{DD} pin where package pins allow; shorted to V_{DDD} otherwise.

VSSA: Analog ground pin where package pins allow; shorted to VSS otherwise

VSS: Ground pin.

VCCD: Regulated Digital supply (1.8 V ±5%).

Port Pins can all be used as LCD Commons, LCD Segment drivers, or CSD sense and shield pins can be connected to AMUXBUS A or B or can all be used as GPIO pins that can be driven by firmware or DSI signals.

The following packages are supported: 44-pin TQFP, 40-pin QFN, and 28-pin SSOP.
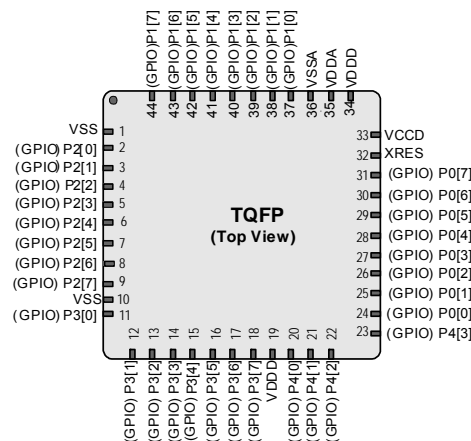
Figure 5. 44-pin TQFP Part Pinout

Figure 6. 40-Pin QFN Pinout
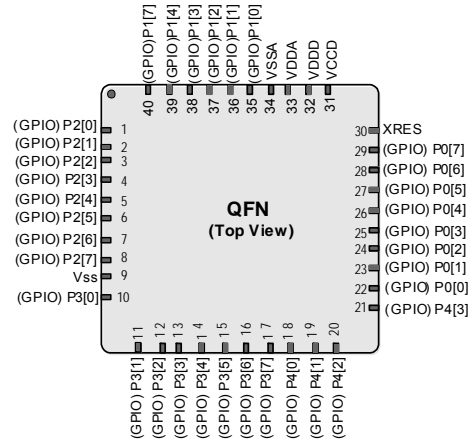
Figure 7. 28-Pin SSOP Pinout
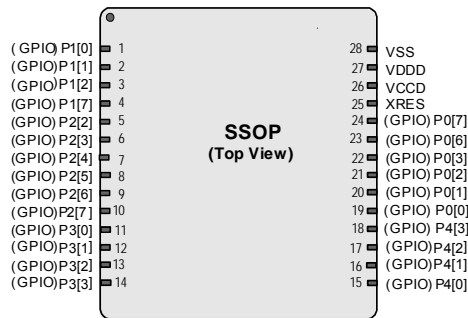
Power

The following power system diagram shows the minimum set of power supply pins as implemented for the PSoC 4200. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the V_{DDA} input. There are separate regulators for the Deep Sleep and Hibernate (lowered power supply and retention) modes. There is a separate low-noise regulator for the bandgap. The supply voltage range is 1.71 to 5.5 V with all functions and circuits operating over that range.

The PSoC 4200 family allows two distinct modes of power supply operation: Unregulated External Supply, and Regulated External Supply modes.

Unregulated External Supply

In this mode, the PSoC 4200 is powered by an External Power Supply that can be anywhere in the range of 1.8 to 5.5V. This range is also designed for battery-powered operation, for instance, the chip can be powered from a battery system that starts at 3.5V and works down to 1.8V. In this mode, the internal regulator of the PSoC 4200 supplies the internal logic and the VCCD output of the PSoC 4200 must be bypassed to ground via an external Capacitor (in the range of 1 to 1.6 µF; X5R ceramic or better).

VDDA and VDDD must be shorted together; the grounds, VSSA and VSS must also be shorted together. Bypass capacitors must be used from VDDD to ground, typical practice for systems in this frequency range is to use a capacitor in the 1 µF range in parallel with a smaller capacitor (0.1 µF for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the Bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme for the 44 TQFP package follows.

Figure 8. 44-TQFP Package Example
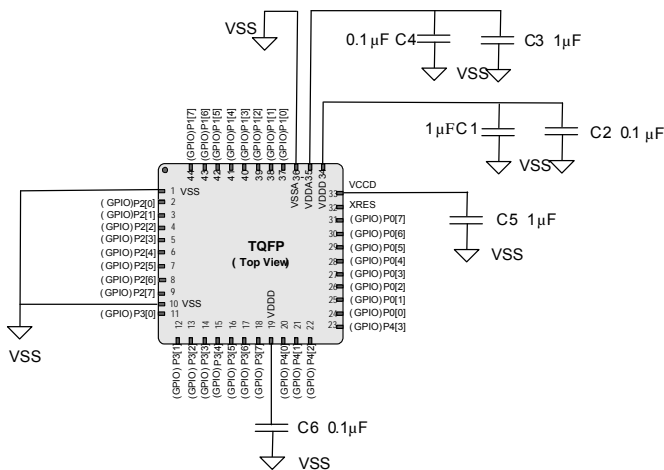
Power Supply	Bypass Capacitors
VDDD–VSS	0.1 µF ceramic at each pin (C2, C6) plus bulk capacitor 1 to 10 µF (C1).
VDDA–VSSA	0.1 µF ceramic at pin (C4). Additional 1 µF to 10 µF (C3) bulk capacitor
VCCD–VSS	1 µF ceramic capacitor at the VCCD pin (C5)
VREF–VSSA (optional)	The internal bandgap may be bypassed with a 1 µF to 10 µF capacitor.

Figure 9. 40-pin QFN Example
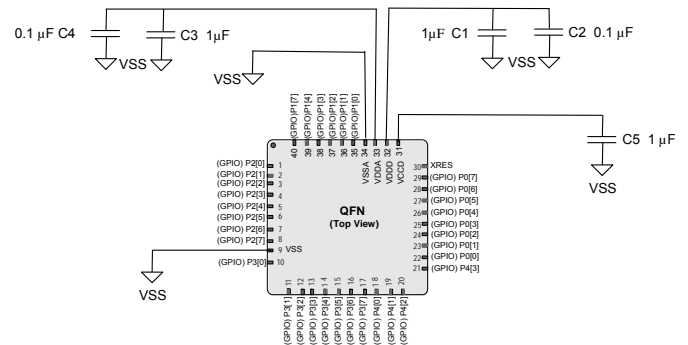
Figure 10. 28-SSOP Example
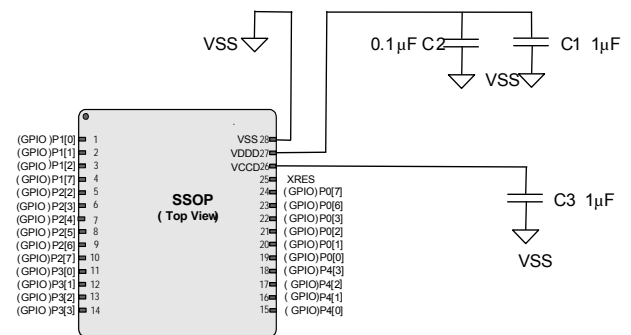
Regulated External Supply

In this mode, the PSoC 4200 is powered by an external power supply that must be within the range of 1.71 to 1.89 V (1.8 ±5%); note that this range needs to include power supply ripple too. In this mode, VCCD, VDDA, and VDDD pins are all shorted together and bypassed. The internal regulator is disabled in firmware.

Development Support

The PSoC 4200 family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit www.cypress.com/go/psoc4 to find out more.

Documentation

A suite of documentation supports the PSoC 4200 family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

Software User Guide: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

Component Datasheets: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

Application Notes: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

Technical Reference Manual: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers.

Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4200 family is part of a development tool ecosystem. Visit us at www.cypress.com/go/psoccreator for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.

Electrical Specifications

Absolute Maximum Ratings

Table 1. Absolute Maximum Ratings[1]

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID1	V_{DDD_ABS}	Digital supply relative to Vssd	−0.5	–	6	V	Absolute max
SID2	V_{CCD_ABS}	Direct digital core voltage input relative to Vssd	−0.5	–	1.95	V	Absolute max
SID3	V_{GPIO_ABS}	GPIO voltage	−0.5	–	V_{DD}+0.5	V	Absolute max
SID4	I_{GPIO_ABS}	Maximum current per GPIO	−25	–	25	mA	Absolute max
SID5	$I_{GPIO\_injection}$	GPIO injection current, Max for V_{IH} > V_{DDD}, and Min for V_{IL} < V_{SS}	−0.5	–	0.5	mA	Absolute max, current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	–	–	V	
BID45	ESD_CDM	Electrostatic discharge charged device model	500	–	–	V	
BID46	LU	Pin current for Latch-up	−200	–	200	mA	

Device Level Specifications

All specifications are valid for -40 °C ≤ TA ≤ 85 °C and TJ ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 2. DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID53	V_{DDD}	Power supply input voltage	1.8	–	5.5	V	With regulator enabled
SID255	V_{DDD}	Power supply input voltage unregulated	1.71	1.8	1.89	V	Internally unregulated supply
SID54	V_{CCD}	Output voltage (for core logic)	–	1.8	–	V	
SID55	C_{EFC}	External regulator voltage bypass	1	1.3	1.6	µF	X5R ceramic or better
SID56	C_{EXC}	Power supply decoupling capacitor	–	1	–	µF	X5R ceramic or better
Active Mode, V_{DDD} = 1.71 to 5.5 V. Typical values measured at V_{DD} = 3.3 V.							
SID9	I_{DD5}	Execute from Flash; CPU at 6 MHz	–	–	2.8	mA	
SID10	I_{DD6}	Execute from Flash; CPU at 6 MHz	–	2.2	–	mA	T = 25 °C
SID12	I_{DD8}	Execute from Flash; CPU at 12 MHz	–	–	4.2	mA	
SID13	I_{DD9}	Execute from Flash; CPU at 12 MHz	–	3.7	–	mA	T = 25 °C
SID16	I_{DD11}	Execute from Flash; CPU at 24 MHz	–	6.7	–	mA	T = 25 °C
SID17	I_{DD12}	Execute from Flash; CPU at 24 MHz	–	–	7.2	mA	
SID19	I_{DD14}	Execute from Flash; CPU at 48 MHz	–	12.8	–	mA	T = 25 °C
SID20	I_{DD15}	Execute from Flash; CPU at 48 MHz	–	–	13.8	mA	

Note
1. Usage above the absolute maximum conditions listed in Table 1 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended periods of time may affect device reliability. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.

Table 2. DC Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
Sleep Mode, V_{DDD} = 3.6 to 5.5 V (Regulator on, 6 MHz)							
SID25	I_{DD20}	I²C wakeup, WDT, and comparators on	–	1200	–	µA	T = 25 °C
Deep Sleep Mode, V_{DDD} = 1.8 to 3.6 V (Regulator on)							
SID31	I_{DD26}	I²C wakeup and WDT on	–	1.3	–	µA	T = 25 °C, 3.6 V
SID32	I_{DD27}	I²C wakeup and WDT on	–	–	50	µA	T = 85 °C
Deep Sleep Mode, V_{DDD} = 3.6 to 5.5 V							
SID34	I_{DD29}	I²C wakeup and WDT on	–	15	–	µA	T = 25 °C, 5.5 V
Deep Sleep Mode, V_{DDD} = 1.71 to 1.89 V (Regulator bypassed)							
SID37	I_{DD32}	I²C wakeup and WDT on	–	1.7	–	µA	T = 25 °C
SID38	I_{DD33}	I²C wakeup and WDT on	–	–	440	µA	T = 85 °C
Hibernate Mode, V_{DDD} = 1.8 to 3.6 V (Regulator on; Guaranteed by Characterization)							
SID40	I_{DD35}	GPIO and reset active	–	150	–	nA	T = 25 °C, 3.6 V
SID41	I_{DD36}	GPIO and reset active	–	–	1	µA	T = 85 °C
Hibernate Mode, V_{DDD} = 3.6 to 5.5 V (Guaranteed by Characterization)							
SID43	I_{DD38}	GPIO and reset active	–	150	–	nA	T = 25 °C, 5.5 V
Hibernate Mode, V_{DDD} = 1.71 to 1.89 V (Regulator bypassed; Guaranteed by Characterization)							
SID46	I_{DD41}	GPIO and reset active	–	150	–	nA	T = 25 °C
SID47	I_{DD42}	GPIO and reset active	–	–	1	µA	T = 85 °C
Stop Mode (Guaranteed by Characterization)							
SID304	I_{DD43A}	Stop Mode current; V_{DD} = 3.6 V	–	20	80	nA	
XRES Current							
SID307	I_{DD_XR}	Supply current while XRES asserted	–	2	5	mA	

Table 3. AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID48	F_{CPU}	CPU frequency	DC	–	48	MHz	$1.71 \leq V_{DD} \leq 5.5$
SID49	T_{SLEEP}	Wakeup from sleep mode	–	0	–	µs	Guaranteed by characterization
SID50	$T_{DEEPSLEEP}$	Wakeup from Deep Sleep mode	–	–	25	µs	24 MHz IMO. Guaranteed by characterization
SID51	$T_{HIBERNATE}$	Wakeup from Hibernate and Stop modes	–	–	2	ms	Guaranteed by characterization
SID52	$T_{RESETWIDTH}$	External reset pulse width	1	–	–	µs	Guaranteed by characterization

GPIO

Table 4. GPIO DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID57	V_{IH}[2]	Input voltage high threshold	$0.7 \times V_{DDD}$	–	–	V	CMOS Input
SID58	V_{IL}	Input voltage low threshold	–	–	$0.3 \times V_{DDD}$	V	CMOS Input
SID241	V_{IH}[2]	LVTTL input, $V_{DDD} < 2.7$ V	$0.7 \times V_{DDD}$	–	–	V	
SID242	V_{IL}	LVTTL input, $V_{DDD} < 2.7$ V	–	–	$0.3 \times V_{DDD}$	V	
SID243	V_{IH}[2]	LVTTL input, $V_{DDD} \geq 2.7$ V	2.0	–	–	V	
SID244	V_{IL}	LVTTL input, $V_{DDD} \geq 2.7$ V	–	–	0.8	V	
SID59	V_{OH}	Output voltage high level	$V_{DDD} -0.6$	–	–	V	I_{OH} = 4 mA at 3 V V_{DDD}
SID60	V_{OH}	Output voltage high level	$V_{DDD} -0.5$	–	–	V	I_{OH} = 1 mA at 1.8 V V_{DDD}
SID61	V_{OL}	Output voltage low level	–	–	0.6	V	I_{OL} = 4 mA at 1.8 V V_{DDD}
SID62	V_{OL}	Output voltage low level	–	–	0.6	V	I_{OL} = 8 mA at 3 V V_{DDD}
SID62A	V_{OL}	Output voltage low level	–	–	0.4	V	I_{OL} = 3 mA at 3 V V_{DDD}
SID63	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5	kΩ	
SID65	I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, V_{DDD} = 3.0 V
SID65A	I_{IL_CTBM}	Input leakage current (absolute value) for CTBM pins	–	–	4	nA	
SID66	C_{IN}	Input capacitance	–	–	7	pF	
SID67	V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DDD} \geq 2.7$ V. Guaranteed by characterization
SID68	$V_{HYSCMOS}$	Input hysteresis CMOS	$0.05 \times V_{DDD}$	–	–	mV	Guaranteed by characterization
SID69	I_{DIODE}	Current through protection diode to V_{DD}/Vss	–	–	100	µA	Guaranteed by characterization
SID69A	I_{TOT_GPIO}	Maximum Total Source or Sink Chip Current	–	–	200	mA	Guaranteed by characterization

Table 5. GPIO AC Specifications (Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	T_{RISEF}	Rise time in fast strong mode	2	–	12	ns	3.3 V V_{DDD}, Cload = 25 pF
SID71	T_{FALLF}	Fall time in fast strong mode	2	–	12	ns	3.3 V V_{DDD}, Cload = 25 pF

Note
2. V_{IH} must not exceed V_{DDD} + 0.2 V.

Table 5. GPIO AC Specifications (Guaranteed by Characterization) *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID72	T_{RISES}	Rise time in slow strong mode	10	–	60		3.3 V V_{DDD}, Cload = 25 pF
SID73	T_{FALLS}	Fall time in slow strong mode	10	–	60		3.3 V V_{DDD}, Cload = 25 pF
SID74	$F_{GPIOUT1}$	GPIO Fout;3.3 V ≤ V_{DDD} ≤ 5.5 V. Fast strong mode.	–	–	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	$F_{GPIOUT2}$	GPIO Fout;1.7 V≤ V_{DDD}≤ 3.3 V. Fast strong mode.	–	–	16.7	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID76	$F_{GPIOUT3}$	GPIO Fout;3.3 V ≤ V_{DDD} ≤ 5.5 V. Slow strong mode.	–	–	7	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID245	$F_{GPIOUT4}$	GPIO Fout;1.7 V ≤ V_{DDD} ≤ 3.3 V. Slow strong mode.	–	–	3.5	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID246	F_{GPIOIN}	GPIO input operating frequency; 1.71 V ≤ V_{DDD} ≤ 5.5 V	–	–	48	MHz	90/10% V_{IO}

XRES

Table 6. XRES DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID77	V_{IH}	Input voltage high threshold	0.7 × V_{DDD}	–	–	V	CMOS Input
SID78	V_{IL}	Input voltage low threshold	–	–	0.3 × V_{DDD}	V	CMOS Input
SID79	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID80	C_{IN}	Input capacitance	–	3	–	pF	
SID81	$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	Guaranteed by characterization
SID82	I_{DIODE}	Current through protection diode to V_{DDD}/V_{SS}	–	–	100	µA	Guaranteed by characterization

Table 7. XRES AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID83	$T_{RESETWIDTH}$	Reset pulse width	1	–	–	µs	Guaranteed by characterization

Analog Peripherals

Opamp

Table 8. Opamp Specifications (Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
	I_{DD}	Opamp block current. No load.	–	–	–	–	
SID269	I_{DD_HI}	Power = high	–	1000	1300	µA	
SID270	I_{DD_MED}	Power = medium	–	320	500	µA	
SID271	I_{DD_LOW}	Power = low	–	250	350	µA	
	GBW	Load = 20 pF, 0.1 mA. V_{DDA} = 2.7 V	–	–	–	–	
SID272	GBW_HI	Power = high	6	–	–	MHz	
SID273	GBW_MED	Power = medium	4	–	–	MHz	
SID274	GBW_LO	Power = low	–	1	–	MHz	
	I_{OUT_MAX}	$V_{DDA} \geq$ 2.7 V, 500 mV from rail	–	–	–	–	
SID275	$I_{OUT\_MAX\_HI}$	Power = high	10	–	–	mA	
SID276	$I_{OUT\_MAX\_MID}$	Power = medium	10	–	–	mA	
SID277	$I_{OUT\_MAX\_LO}$	Power = low	–	5	–	mA	
	I_{OUT}	V_{DDA} = 1.71 V, 500 mV from rail	–	–	–	–	
SID278	$I_{OUT\_MAX\_HI}$	Power = high	4	–	–	mA	
SID279	$I_{OUT\_MAX\_MID}$	Power = medium	4	–	–	mA	
SID280	$I_{OUT\_MAX\_LO}$	Power = low	–	2	–	mA	
SID281	V_{IN}	Charge pump on, $V_{DDA} \geq$ 2.7 V	–0.05	–	VDDA – 0.2	V	
SID282	V_{CM}	Charge pump on, $V_{DDA} \geq$ 2.7 V	–0.05	–	VDDA – 0.2	V	
	V_{OUT}	$V_{DDA} \geq$ 2.7 V	–	–	–		
SID283	V_{OUT_1}	Power = high, Iload=10 mA	0.5	–	VDDA – 0.5	V	
SID284	V_{OUT_2}	Power = high, Iload=1 mA	0.2	–	VDDA – 0.2	V	
SID285	V_{OUT_3}	Power = medium, Iload=1 mA	0.2	–	VDDA – 0.2	V	
SID286	V_{OUT_4}	Power = low, Iload=0.1mA	0.2	–	VDDA – 0.2	V	
SID288	V_{OS_TR}	Offset voltage, trimmed	1	±0.5	1	mV	High mode
SID288A	V_{OS_TR}	Offset voltage, trimmed	–	±1	–	mV	Medium mode
SID288B	V_{OS_TR}	Offset voltage, trimmed	–	±2	–	mV	Low mode
SID290	$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–10	±3	10	µV/C	High mode
SID290A	$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–	±10	–	µV/C	Medium mode
SID290B	$V_{OS\_DR\_TR}$	Offset voltage drift, trimmed	–	±10	–	µV/C	Low mode
SID291	CMRR	DC	70	80	–	dB	VDDD = 3.6 V
SID292	PSRR	At 1 kHz, 100 mV ripple	70	85	–	dB	VDDD = 3.6 V
	Noise		–	–	–	–	
SID293	V_{N1}	Input referred, 1 Hz - 1GHz, power = high	–	94	–	µVrms	
SID294	V_{N2}	Input referred, 1 kHz, power = high	–	72	–	nV/rtHz	
SID295	V_{N3}	Input referred, 10kHz, power = high	–	28	–	nV/rtHz	
SID296	V_{N4}	Input referred, 100kHz, power = high	–	15	–	nV/rtHz	
SID297	Cload	Stable up to maximum load. Performance specs at 50 pF.	–	–	125	pF	

Table 8. Opamp Specifications (Guaranteed by Characterization) *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID298	Slew_rate	Cload = 50 pF, Power = High, $V_{DDA} \geq$ 2.7 V	6	–	–	V/μsec	
SID299	T_op_wake	From disable to enable, no external RC dominating	–	300	–	μsec	
	Comp_mode	Comparator mode; 50 mV drive, Trise = Tfall (approx.)	–	–	–		
SID300	T_{PD1}	Response time; power = high	–	150	–	nsec	
SID301	T_{PD2}	Response time; power = medium	–	400	–	nsec	
SID302	T_{PD3}	Response time; power = low	–	2000	–	nsec	
SID303	Vhyst_op	Hysteresis	–	10	–	mV	

Comparator

Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID85	$V_{OFFSET2}$	Input offset voltage, trimmed	–	–	±4	mV	
SID86	V_{HYST}	Hysteresis when enabled	–	10	35	mV	Guaranteed by characterization
SID87	V_{ICM1}	Input common mode voltage in normal mode	0	–	$V_{DDD} - 0.1$	V	Modes 1 and 2. Guaranteed by characterization
SID247	V_{ICM2}	Input common mode voltage in low power mode	0	–	V_{DDD}	V	Guaranteed by characterization
SID247A	V_{ICM2}	Input common mode voltage in ultra low power mode	0	–	$V_{DDD} -$ 1.15	V	Guaranteed by characterization
SID88	CMRR	Common mode rejection ratio	50	–	–	dB	$V_{DDD} \geq 2.7$ V. Guaranteed by characterization
SID88A	CMRR	Common mode rejection ratio	42	–	–	dB	$V_{DDD} < 2.7$ V. Guaranteed by characterization
SID89	I_{CMP1}	Block current, normal mode	–	–	280	μA	Guaranteed by characterization
SID248	I_{CMP2}	Block current, low power mode	–	–	50	μA	Guaranteed by characterization
SID259	I_{CMP3}	Block current, ultra low power mode	–	–	6	μA	Guaranteed by characterization
SID90	Z_{CMP}	DC input impedance of comparator	35	–	–	MΩ	Guaranteed by characterization

Table 10. Comparator AC Specifications (Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID91	T_{RESP1}	Response time, normal mode	–	–	38	ns	50 mV overdrive
SID258	T_{RESP2}	Response time, low power mode	–	–	70	ns	50 mV overdrive
SID92	T_{RESP3}	Response time, ultra low power mode	–	–	2.3	μs	200 mV overdrive

Temperature Sensor

Table 11. Temperature Sensor Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID93	T$_{SENSACC}$	Temperature sensor accuracy	–5	±1	+5	°C	–40 to +85 °C

SAR ADC

Table 12. SAR ADC DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID94	A_RES	Resolution	–	–	12	bits	
SID95	A_CHNIS_S	Number of channels - single ended	–	–	8		8 full speed
SID96	A-CHNKS_D	Number of channels - differential	–	–	4		Diff inputs use neighboring I/O
SID97	A-MONO	Monotonicity	–	–	–		Yes. Based on characterization
SID98	A_GAINERR	Gain error	–	–	±0.1	%	With external reference. Guaranteed by characterization
SID99	A_OFFSET	Input offset voltage	–	–	2	mV	Measured with 1-V V$_{REF.}$ Guaranteed by characterization
SID100	A_ISAR	Current consumption	–	–	1	mA	
SID101	A_VINS	Input voltage range - single ended	V$_{SS}$	–	V$_{DDA}$	V	Based on device characterization
SID102	A_VIND	Input voltage range - differential	V$_{SS}$	–	V$_{DDA}$	V	Based on device characterization
SID103	A_INRES	Input resistance	–	–	2.2	KΩ	Based on device characterization
SID104	A_INCAP	Input capacitance	–	–	10	pF	Based on device characterization

Table 13. SAR ADC AC Specifications (Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID106	A_PSRR	Power supply rejection ratio	70	–	–	dB	
SID107	A_CMRR	Common mode rejection ratio	66	–	–	dB	Measured at 1 V
SID108	A_SAMP	Sample rate	–	–	1	Msps	
SID109	A_SNDR	Signal-to-noise and distortion ratio (SINAD)	65	–	–	dB	F$_{IN}$ = 10 kHz
SID111	A_INL	Integral non linearity	–1.7	–	+2	LSB	V$_{DD}$ = 1.71 to 5.5, 1 Msps, Vref = 1 to 5.5.
SID111A	A_INL	Integral non linearity	–1.5	–	+1.7	LSB	V$_{DDD}$ = 1.71 to 3.6, 1 Msps, Vref = 1.71 to V$_{DDD}$.
SID111B	A_INL	Integral non linearity	–1.5	–	+1.7	LSB	V$_{DDD}$ = 1.71 to 5.5, 500 Ksps, Vref = 1 to 5.5.

Table 13. SAR ADC AC Specifications (Guaranteed by Characterization) *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID112	A_DNL	Differential non linearity	−1	–	+2.2	LSB	V_{DDD} = 1.71 to 5.5, 1 Msps, Vref = 1 to 5.5.
SID112A	A_DNL	Differential non linearity	−1	–	+2	LSB	V_{DDD} = 1.71 to 3.6, 1 Msps, Vref = 1.71 to V_{DDD}.
SID112B	A_DNL	Differential non linearity	−1	–	+2.2	LSB	V_{DDD} = 1.71 to 5.5, 500 Ksps, Vref = 1 to 5.5.
SID113	A_THD	Total harmonic distortion	–	–	−65	dB	F_{IN} = 10 kHz.

CSD

Table 14. CSD Block Specification

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
CSD Specification							
SID308	VCSD	Voltage range of operation	1.71	–	5.5	V	
SID309	IDAC1	DNL for 8-bit resolution	−1	–	1	LSB	
SID310	IDAC1	INL for 8-bit resolution	−3	–	3	LSB	
SID311	IDAC2	DNL for 7-bit resolution	−1	–	1	LSB	
SID312	IDAC2	INL for 7-bit resolution	−3	–	3	LSB	
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	–	–	Ratio	Capacitance range of 9 to 35 pF, 0.1 pF sensitivity
SID314	IDAC1_CRT1	Output current of Idac1 (8-bits) in High range	–	612	–	µA	
SID314A	IDAC1_CRT2	Output current of Idac1(8-bits) in Low range	–	306	–	µA	
SID315	IDAC2_CRT1	Output current of Idac2 (7-bits) in High range	–	304.8	–	µA	
SID315A	IDAC2_CRT2	Output current of Idac2 (7-bits) in Low range	–	152.4	–	µA	

Digital Peripherals

The following specifications apply to the Timer/Counter/PWM peripheral in timer mode.

Timer

Table 15. Timer DC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID115	I_{TIM1}	Block current consumption at 3 MHz	–	–	19	µA	16-bit timer
SID116	I_{TIM2}	Block current consumption at 12 MHz	–	–	66	µA	16-bit timer
SID117	I_{TIM3}	Block current consumption at 48 MHz	–	–	285	µA	16-bit timer

Table 16. Timer AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID118	$T_{TIMFREQ}$	Operating frequency	–	–	48	MHz	
SID119	$T_{CAPWINT}$	Capture pulse width (internal)	42	–	–	ns	
SID120	$T_{CAPWEXT}$	Capture pulse width (external)	42	–	–	ns	
SID121	T_{TIMRES}	Timer resolution	21	–	–	ns	
SID122	$T_{TENWIDINT}$	Enable pulse width (internal)	42	–	–	ns	
SID123	$T_{TENWIDEXT}$	Enable pulse width (external)	42	–	–	ns	
SID124	$T_{TIMRESWINT}$	Reset pulse width (internal)	42	–	–	ns	
SID125	$T_{TIMRESEXT}$	Reset pulse width (external)	42	–	–	ns	

Counter

Table 17. Counter DC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID126	I_{CTR1}	Block current consumption at 3 MHz	–	–	19	µA	16-bit Counter
SID127	I_{CTR2}	Block current consumption at 12 MHz	–	–	66	µA	16-bit Counter
SID128	I_{CTR3}	Block current consumption at 48 MHz	–	–	285	µA	16-bit Counter

Table 18. Counter AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID129	$T_{CTRFREQ}$	Operating frequency	–	–	48	MHz	
SID130	$T_{CTRPWINT}$	Capture pulse width (internal)	42	–	–	ns	
SID131	$T_{CTRPWEXT}$	Capture pulse width (external)	42	–	–	ns	
SID132	T_{CTRES}	Counter Resolution	21	–	–	ns	
SID133	$T_{CENWIDINT}$	Enable pulse width (internal)	42	–	–	ns	
SID134	$T_{CENWIDEXT}$	Enable pulse width (external)	42	–	–	ns	
SID135	$T_{CTRRESWINT}$	Reset pulse width (internal)	42	–	–	ns	
SID136	$T_{CTRRESWEXT}$	Reset pulse width (external)	42	–	–	ns	

Pulse Width Modulation (PWM)

Table 19. PWM DC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID137	I_{PWM1}	Block current consumption at 3 MHz	–	–	19	µA	16-bit PWM
SID138	I_{PWM2}	Block current consumption at 12 MHz	–	–	66	µA	16-bit PWM
SID139	I_{PWM3}	Block current consumption at 48 MHz	–	–	285	µA	16-bit PWM

Table 20. PWM AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID140	$T_{PWMFREQ}$	Operating frequency	–	–	48	MHz	
SID141	$T_{PWMPWINT}$	Pulse width (internal)	42	–	–	ns	
SID142	T_{PWMEXT}	Pulse width (external)	42	–	–	ns	
SID143	$T_{PWMKILLINT}$	Kill pulse width (internal)	42	–	–	ns	
SID144	$T_{PWMKILLEXT}$	Kill pulse width (external)	42	–	–	ns	
SID145	$T_{PWMEINT}$	Enable pulse width (internal)	42	–	–	ns	
SID146	$T_{PWMENEXT}$	Enable pulse width (external)	42	–	–	ns	
SID147	$T_{PWMRESWINT}$	Reset pulse width (internal)	42	–	–	ns	
SID148	$T_{PWMRESWEXT}$	Reset pulse width (external)	42	–	–	ns	

I^2C

Table 21. Fixed I^2C DC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID149	I_{I2C1}	Block current consumption at 100 kHz	–	–	10.5	µA	
SID150	I_{I2C2}	Block current consumption at 400 kHz	–	–	135	µA	
SID151	I_{I2C3}	Block current consumption at 1 Mbps	–	–	310	µA	
SID152	I_{I2C4}	I^2C enabled in Deep Sleep mode	–	–	1.4	µA	

Table 22. Fixed I^2C AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID153	F_{I2C1}	Bit rate	–	–	1	Mbps	

LCD Direct Drive

Table 23. LCD Direct Drive DC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID154	I_{LCDLOW}	Operating current in low power mode	–	5	–	µA	16 × 4 small segment disp. at 50 Hz
SID155	C_{LCDCAP}	LCD capacitance per segment/common driver	–	500	5000	pF	Guaranteed by Design
SID156	LCD_{OFFSET}	Long-term segment offset	–	20	–	mV	
SID157	I_{LCDOP1}	LCD system operating current. Vbias = 5 V	–	2	–	mA	32 × 4 segments. 50 Hz, 25 °C
SID158	I_{LCDOP2}	LCD system operating current Vbias = 3.3 V	–	2	–	mA	32 × 4 segments. 50 Hz, 25 °C

Table 24. LCD Direct Drive AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F_{LCD}	LCD frame rate	10	50	150	Hz	

Table 25. Fixed UART DC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I_{UART1}	Block current consumption at 100 Kbits/sec	–	–	9	µA	
SID161	I_{UART2}	Block current consumption at 1000 Kbits/sec	–	–	312	µA	

Table 26. Fixed UART AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units
SID162	F_{UART}	Bit rate	–	–	1	Mbps

SPI Specifications

Table 27. Fixed SPI DC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units
SID163	I_{SPI1}	Block current consumption at 1 Mbits/sec	–	–	360	µA
SID164	I_{SPI2}	Block current consumption at 4 Mbits/sec	–	–	560	µA
SID165	I_{SPI3}	Block current consumption at 8 Mbits/sec	–	–	600	µA

Table 28. Fixed SPI AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units
SID166	F_{SPI}	SPI operating frequency (master; 6X oversampling)	–	–	8	MHz

Table 29. Fixed SPI Master mode AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units
SID167	T_{DMO}	MOSI valid after Sclock driving edge	–	–	15	ns
SID168	T_{DSI}	MISO valid before Sclock capturing edge. Full clock, late MISO Sampling used	20	–	–	ns
SID169	T_{HMO}	Previous MOSI data hold time with respect to capturing edge at Slave	0	–	–	ns

Table 30. Fixed SPI Slave mode AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units
SID170	T_{DMI}	MOSI valid before Sclock capturing edge	40	–	–	ns
SID171	T_{DSO}	MISO valid after Sclock driving edge	–	–	42 + 3 × FCPU	ns
SID171A	T_{DSO_ext}	MISO valid after Sclock driving edge in Ext. Clock mode	–	–	48	ns
SID172	T_{HSO}	Previous MISO data hold time	0	–	–	ns
SID172A	$T_{SSELSCK}$	SSEL Valid to first SCK Valid edge	100	–	–	ns

Memory

Table 31. Flash DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID173	V_{PE}	Erase and program voltage	1.71	–	5.5	V	

Table 32. Flash AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID174	$T_{ROWWRITE}$[3]	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 128 bytes
SID175	$T_{ROWERASE}$[3]	Row erase time	–	–	13	ms	
SID176	$T_{ROWPROGRAM}$[3]	Row program time after erase	–	–	7	ms	
SID178	$T_{BULKERASE}$[3]	Bulk erase time (32 KB)	–	–	35	ms	
SID180	$T_{DEVPROG}$[3]	Total device program time	–	–	7	seconds	Guaranteed by characterization
SID181	F_{END}	Flash endurance	100 K	–	–	cycles	Guaranteed by characterization
SID182	F_{RET}	Flash retention. $T_A \le 55$ °C, 100 K P/E cycles	20	–	–	years	Guaranteed by characterization
SID182A		Flash retention. $T_A \le 85$ °C, 10 K P/E cycles	10	–	–	years	Guaranteed by characterization

System Resources

Power-on-Reset (POR) with Brown Out

Table 33. Imprecise Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID185	$V_{RISEIPOR}$	Rising trip voltage	0.80	–	1.45	V	Guaranteed by characterization
SID186	$V_{FALLIPOR}$	Falling trip voltage	0.75	–	1.4	V	Guaranteed by characterization
SID187	$V_{IPORHYST}$	Hysteresis	15	–	200	mV	Guaranteed by characterization

Table 34. Precise Power On Reset (POR)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID190	$V_{FALLPPOR}$	BOD trip voltage in active and sleep modes	1.64	–	–	V	Guaranteed by characterization
SID192	$V_{FALLDPSLP}$	BOD trip voltage in Deep Sleep	1.4	–	–	V	Guaranteed by characterization

Note
3. It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.

Voltage Monitors

Table 35. Voltage Monitors DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID195	V_{LVI1}	LVI_A/D_SEL[3:0] = 0000b	1.71	1.75	1.79	V	
SID196	V_{LVI2}	LVI_A/D_SEL[3:0] = 0001b	1.76	1.80	1.85	V	
SID197	V_{LVI3}	LVI_A/D_SEL[3:0] = 0010b	1.85	1.90	1.95	V	
SID198	V_{LVI4}	LVI_A/D_SEL[3:0] = 0011b	1.95	2.00	2.05	V	
SID199	V_{LVI5}	LVI_A/D_SEL[3:0] = 0100b	2.05	2.10	2.15	V	
SID200	V_{LVI6}	LVI_A/D_SEL[3:0] = 0101b	2.15	2.20	2.26	V	
SID201	V_{LVI7}	LVI_A/D_SEL[3:0] = 0110b	2.24	2.30	2.36	V	
SID202	V_{LVI8}	LVI_A/D_SEL[3:0] = 0111b	2.34	2.40	2.46	V	
SID203	V_{LVI9}	LVI_A/D_SEL[3:0] = 1000b	2.44	2.50	2.56	V	
SID204	V_{LVI10}	LVI_A/D_SEL[3:0] = 1001b	2.54	2.60	2.67	V	
SID205	V_{LVI11}	LVI_A/D_SEL[3:0] = 1010b	2.63	2.70	2.77	V	
SID206	V_{LVI12}	LVI_A/D_SEL[3:0] = 1011b	2.73	2.80	2.87	V	
SID207	V_{LVI13}	LVI_A/D_SEL[3:0] = 1100b	2.83	2.90	2.97	V	
SID208	V_{LVI14}	LVI_A/D_SEL[3:0] = 1101b	2.93	3.00	3.08	V	
SID209	V_{LVI15}	LVI_A/D_SEL[3:0] = 1110b	3.12	3.20	3.28	V	
SID210	V_{LVI16}	LVI_A/D_SEL[3:0] = 1111b	4.39	4.50	4.61	V	
SID211	LVI_IDD	Block current	–	–	100	µA	Guaranteed by characterization

Table 36. Voltage Monitors AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID212	$T_{MONTRIP}$	Voltage monitor trip time	–	–	1	µs	Guaranteed by characterization

SWD Interface

Table 37. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWDCLK1	3.3 V ≤ V_{DD} ≤ 5.5 V	–	–	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	1.71 V ≤ V_{DD} ≤ 3.3 V	–	–	7	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID215	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID216	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID217	T_SWDO_VALID	T = 1/f SWDCLK	–	–	0.5*T	ns	Guaranteed by characterization
SID217A	T_SWDO_HOLD	T = 1/f SWDCLK	1	–	–	ns	Guaranteed by characterization

Internal Main Oscillator

Table 38. IMO DC Specifications (Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I_{IMO1}	IMO operating current at 48 MHz	–	–	1000	µA	
SID219	I_{IMO2}	IMO operating current at 24 MHz	–	–	325	µA	
SID220	I_{IMO3}	IMO operating current at 12 MHz	–	–	225	µA	
SID221	I_{IMO4}	IMO operating current at 6 MHz	–	–	180	µA	
SID222	I_{IMO5}	IMO operating current at 3 MHz	–	–	150	µA	

Table 39. IMO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	$F_{IMOTOL1}$	Frequency variation from 3 to 48 MHz	–	–	±2	%	With API-called calibration
SID226	$T_{STARTIMO}$	IMO startup time	–	–	12	µs	
SID227	$T_{JITRMSIMO1}$	RMS Jitter at 3 MHz	–	156	–	ps	
SID228	$T_{JITRMSIMO2}$	RMS Jitter at 24 MHz	–	145	–	ps	
SID229	$T_{JITRMSIMO3}$	RMS Jitter at 48 MHz	–	139	–	ps	

Internal Low-Speed Oscillator

Table 40. ILO DC Specifications (Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231	I_{ILO1}	ILO operating current at 32 kHz	–	0.3	1.05	µA	Guaranteed by Characterization
SID233	$I_{ILOLEAK}$	ILO leakage current	–	2	15	nA	Guaranteed by Design

Table 41. ILO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234	$T_{STARTILO1}$	ILO startup time	–	–	2	ms	Guaranteed by characterization
SID236	$T_{ILODUTY}$	ILO duty cycle	40	50	60	%	Guaranteed by characterization
SID237	$F_{ILOTRIM1}$	32 kHz trimmed frequency	15	32	50	kHz	±60% with trim.

Table 42. External Clock Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID305	ExtClkFreq	External Clock input Frequency	0	–	48	MHz	Guaranteed by characterization
SID306	ExtClkDuty	Duty cycle; Measured at $V_{DD/2}$	45	–	55	%	Guaranteed by characterization

Table 43. UDB AC Specifications (Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
Datapath performance							
SID249	$F_{MAX-TIMER}$	Max frequency of 16-bit timer in a UDB pair	–	–	48	MHz	
SID250	$F_{MAX-ADDER}$	Max frequency of 16-bit adder in a UDB pair	–	–	48	MHz	
SID251	F_{MAX_CRC}	Max frequency of 16-bit CRC/PRS in a UDB pair	–	–	48	MHz	
PLD Performance in UDB							
SID252	F_{MAX_PLD}	Max frequency of 2-pass PLD function in a UDB pair	–	–	48	MHz	
Clock to Output Performance							
SID253	$T_{CLK\_OUT\_UDB1}$	Prop. delay for clock in to data out at 25 °C, Typ.	–	15	–	ns	
SID254	$T_{CLK\_OUT\_UDB2}$	Prop. delay for clock in to data out, Worst case.	–	25	–	ns	

Table 44. Block Specs

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID256*	T_{WS48}*	Number of wait states at 48 MHz	1	–	–		CPU execution from Flash. Guaranteed by characterization
SID257	T_{WS24}*	Number of wait states at 24 MHz	0	–	–		CPU execution from Flash. Guaranteed by characterization
SID260	V_{REFSAR}	Trimmed internal reference to SAR	–1	–	+1	%	Percentage of Vbg (1.024 V). Guaranteed by characterization
SID262	$T_{CLKSWITCH}$	Clock switching from clk1 to clk2 in clk1 periods	3	–	4	Periods	. Guaranteed by design
* Tws48 and Tws24 are guaranteed by Design							

Table 45. UDB Port Adaptor Specifications (based on LPC Component Specs, Guaranteed by Characterization)

(10 pF load, 3 V V_{DDIO} and V_{DDD})

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID263	T_{LCLKDO}	LCLK to output delay	–	–	18	ns	
SID264	$T_{DINLCLK}$	Input setup time to LCLCK rising edge	–	–	7	ns	
SID265	$T_{DINLCLKHLD}$	Input hold time from LCLK rising edge	5	–	–	ns	
SID266	$T_{LCLKHIZ}$	LCLK to output tristated	–	–	28	ns	
SID267	T_{FLCLK}	LCLK frequency	–	–	33	MHz	
SID268	$T_{LCLKDUTY}$	LCLK duty cycle (percentage high)	40	–	60	%	

Ordering Information

The PSoC 4200 part numbers and features are listed in the following table.
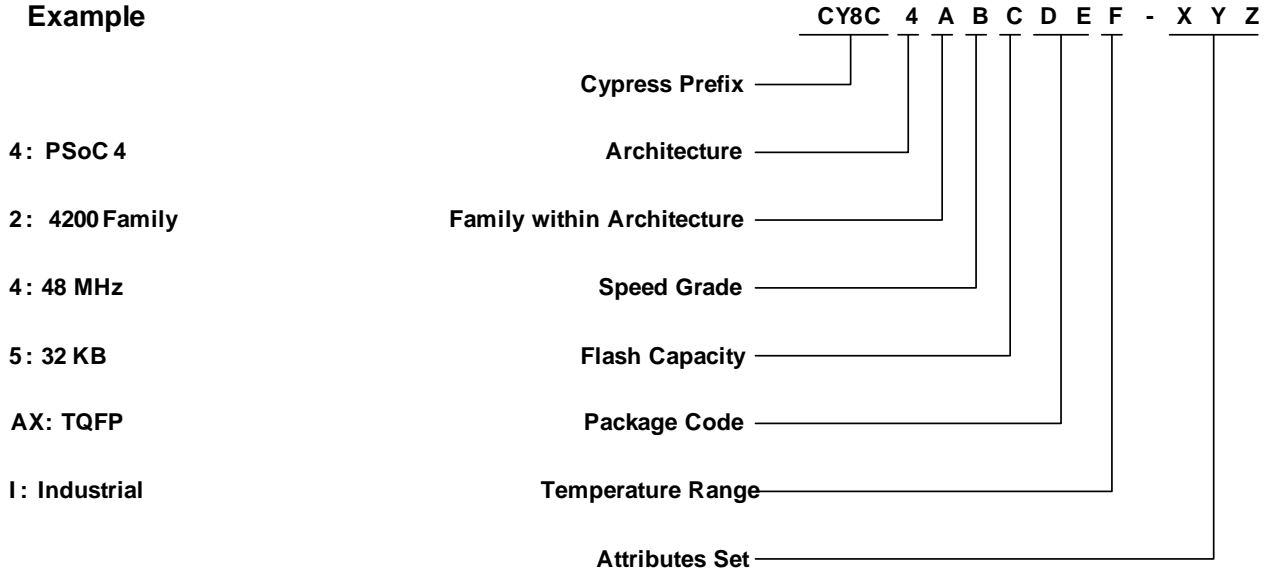
Table 46. PSoC 4200 Family Ordering Information

| Family | MPN | Features | | | | | | | | | | | | Package | | | Silicon ID |
		Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	UDB	Op-amp (CTBm)	CapSense	Direct LCD Drive	12-bit SAR ADC	LP Comparators	TCPWM Blocks	SCB Blocks	GPIO	28-SSOP	40-QFN	44-TQFP	
4200	CY8C4244PVI-432	48	16	4	2	1	–	–	1 Msps	2	4	2	22	✔	–	–	04F0
	CY8C4244PVI-442	48	16	4	2	1	✔	✔	1 Msps	2	4	2	22	✔	–	–	04F1
	CY8C4244LQI-443	48	16	4	2	2	✔	✔	1 Msps	2	4	2	34	–	✔	–	04F6
	CY8C4244AXI-443	48	16	4	2	2	✔	✔	1 Msps	2	4	2	36	–	–	✔	04FA
	CY8C4245AXI-473	48	32	4	4	2	–	–	1 Msps	2	4	2	36	–	–	✔	04FB
	CY8C4245PVI-482	48	32	4	4	1	✔	✔	1 Msps	2	4	2	22	✔	–	–	04A6
	CY8C4245LQI-483	48	32	4	4	2	✔	✔	1 Msps	2	4	2	34	–	✔	–	04B6
	CY8C4245AXI-483	48	32	4	4	2	✔	✔	1 Msps	2	4	2	36	–	–	✔	04C8

Part Numbering Conventions

PSoC 4 devices follow the part numbering convention described in the following table. All fields are single-character alphanumeric (0, 1, 2, …, 9, A,B, …, Z) unless stated otherwise.

The part numbers are of the form CY8C4ABCDEF-XYZ where the fields are defined as follows.

| **Example** | | | | | | | | | | | | CY8C | 4 | A | B | C | D | E | F | - | X | Y | Z |

	Cypress Prefix
4 : PSoC 4	Architecture
2 : 4200 Family	Family within Architecture
4 : 48 MHz	Speed Grade
5 : 32 KB	Flash Capacity
AX: TQFP	Package Code
I : Industrial	Temperature Range
	Attributes Set

The Field Values are listed in the following table.

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
A	Family within archi-tecture	1	4100 Family
		2	4200 Family
B	CPU Speed	2	24 MHz
		4	48 MHz
C	Flash Capacity	4	16 KB
		5	32 KB
DE	Package Code	AX	TQFP
		LQ	QFN
		PV	SSOP
F	Temperature Range	I	Industrial
XYZ	Attributes Code	000-999	Code of feature set in specific family

Packaging

Table 47. Package Characteristics

Parameter	Description	Conditions	Min	Typ	Max	Units
T_A	Operating ambient temperature		–40	25.00	85	°C
T_J	Operating junction temperature		–40	–	100	°C
T_{JA}	Package θ_{JA} (28-pin SSOP)		–	66.58	–	°C/Watt
T_{JA}	Package θ_{JA} (40-pin QFN)		–	15.34	–	°C/Watt
T_{JA}	Package θ_{JA} (44-pin TQFP)		–	57.16	–	°C/Watt
T_{JC}	Package θ_{JC} (28-pin SSOP)		–	26.28	–	°C/Watt
T_{JC}	Package θ_{JC} (40-pin QFN)		–	2.50	–	°C/Watt
T_{JC}	Package θ_{JC} (44-pin TQFP)		–	17.47	–	°C/Watt

Table 48. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
28-pin SSOP	260 °C	30 seconds
40-pin QFN	260 °C	30 seconds
44-pin TQFP	260 °C	30 seconds

Table 49. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-2

Package	MSL
28-pin SSOP	MSL 3
40-pin QFN	MSL 3
44-pin TQFP	MSL 3

Figure 11. 28-pin (210-mil) SSOP Package Outline
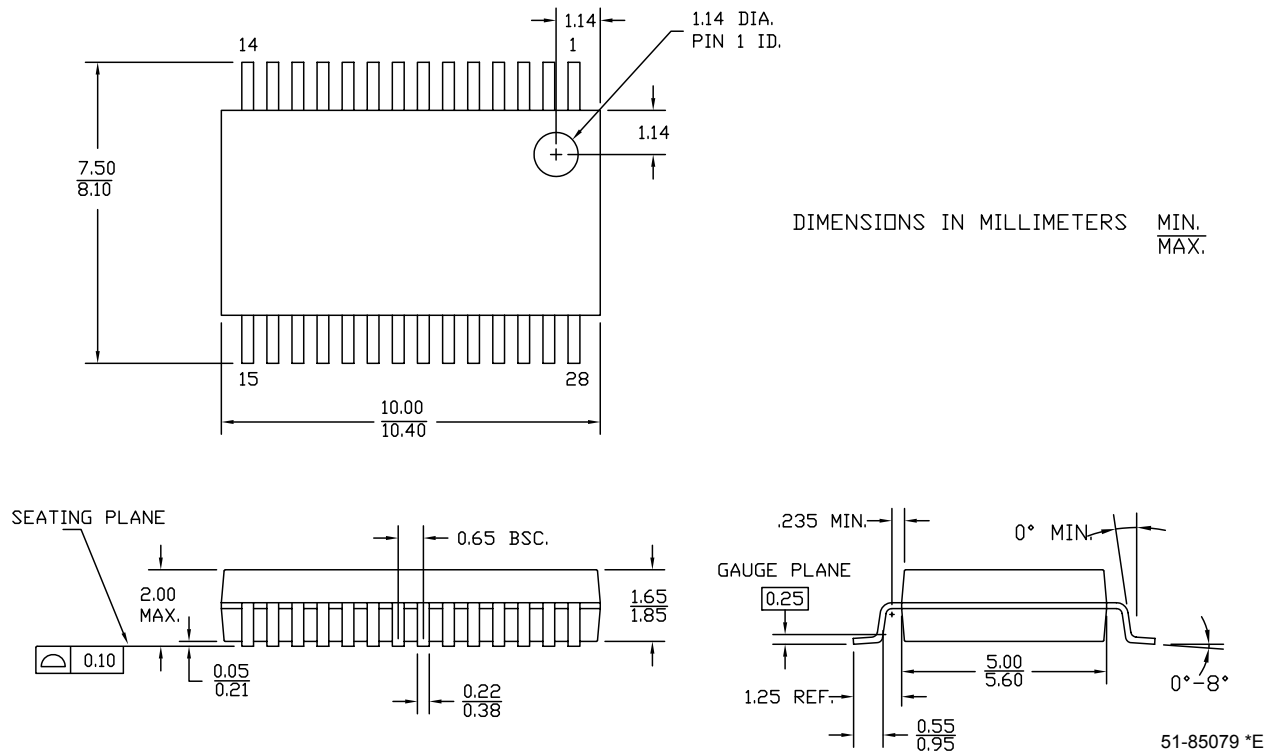
Figure 12. 40-pin QFN Package Outline

TOP VIEW   **SIDE VIEW**   **BOTTOM VIEW**
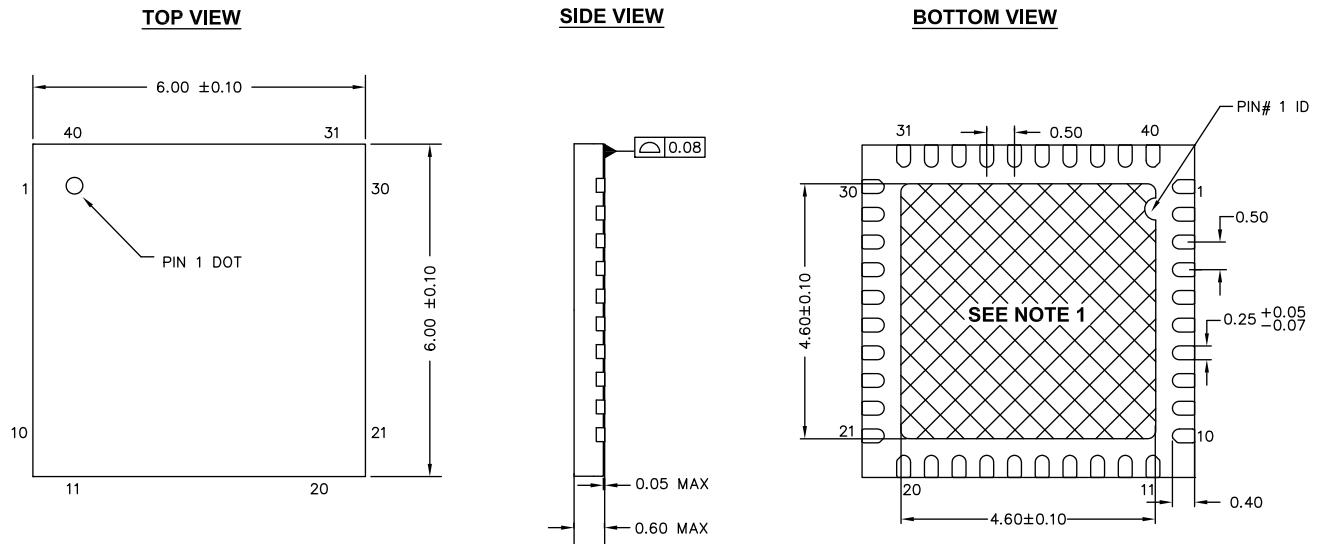
NOTES:

1. ▨ HATCH AREA IS SOLDERABLE EXPOSED PAD

2. REFERENCE JEDEC # MO-248

3. PACKAGE WEIGHT: 68 ±2 mg

4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 **

Figure 13. 44-pin TQFP Package Outline
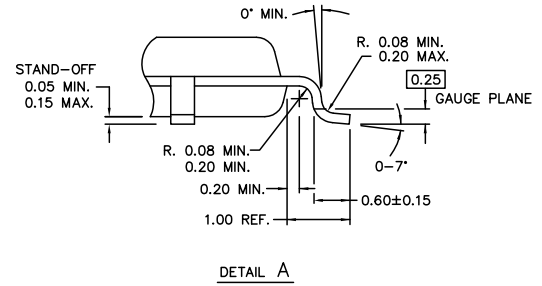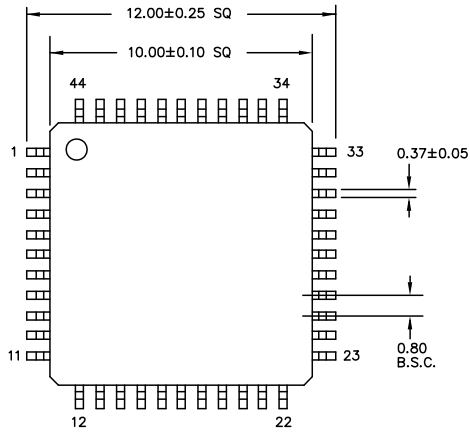
NOTE:

1. JEDEC STD REF MS−026

2. BODY LENGTH DIMENSION DOES NOT INCLUDE MOLD PROTRUSION/END FLASH
   MOLD PROTRUSION/END FLASH SHALL NOT EXCEED 0.0098 in (0.25 mm) PER SIDE
   BODY LENGTH DIMENSIONS ARE MAX PLASTIC BODY SIZE INCLUDING MOLD MISMATCH

3. DIMENSIONS IN MILLIMETERS
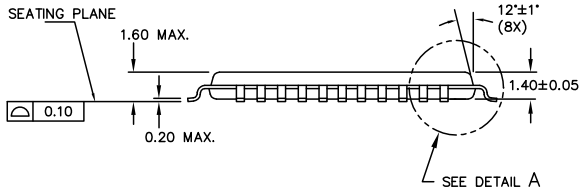
51-85064 *E

Acronyms

Table 50. Acronyms Used in this Document

Acronym	Description
abus	analog local bus
ADC	analog-to-digital converter
AG	analog global
AHB	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus
ALU	arithmetic logic unit
AMUXBUS	analog multiplexer bus
API	application programming interface
APSR	application program status register
ARM®	advanced RISC machine, a CPU architecture
ATM	automatic thump mode
BW	bandwidth
CAN	Controller Area Network, a communications protocol
CMRR	common-mode rejection ratio
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
DAC	digital-to-analog converter, see also IDAC, VDAC
DFB	digital filter block
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.
DMIPS	Dhrystone million instructions per second
DMA	direct memory access, see also TD
DNL	differential nonlinearity, see also INL
DNU	do not use
DR	port write data registers
DSI	digital system interconnect
DWT	data watchpoint and trace
ECC	error correcting code
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
EMI	electromagnetic interference
EMIF	external memory interface
EOC	end of conversion
EOF	end of frame
EPSR	execution program status register
ESD	electrostatic discharge

Table 50. Acronyms Used in this Document (continued)

Acronym	Description
ETM	embedded trace macrocell
FIR	finite impulse response, see also IIR
FPB	flash patch and breakpoint
FS	full-speed
GPIO	general-purpose input/output, applies to a PSoC pin
HVI	high-voltage interrupt, see also LVI, LVD
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
I2C, or IIC	Inter-Integrated Circuit, a communications protocol
IIR	infinite impulse response, see also FIR
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
I/O	input/output, see also GPIO, DIO, SIO, USBIO
IPOR	initial power-on reset
IPSR	interrupt program status register
IRQ	interrupt request
ITM	instrumentation trace macrocell
LCD	liquid crystal display
LIN	Local Interconnect Network, a communications protocol.
LR	link register
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVI	low-voltage interrupt, see also HVI
LVTTL	low-voltage transistor-transistor logic
MAC	multiply-accumulate
MCU	microcontroller unit
MISO	master-in slave-out
NC	no connect
NMI	nonmaskable interrupt
NRZ	non-return-to-zero
NVIC	nested vectored interrupt controller
NVL	nonvolatile latch, see also WOL
opamp	operational amplifier
PAL	programmable array logic, see also PLD

Table 50. Acronyms Used in this Document *(continued)*

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I^2C serial clock
SDA	I^2C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

Table 50. Acronyms Used in this Document *(continued)*

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

Document Conventions

Units of Measure

Table 51. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
µA	microampere
µF	microfarad
µH	microhenry
µs	microsecond
µV	microvolt
µW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt

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